

# Pinch Plasma EUV Source with Particle Injection

Malcolm W. McGeoch    mcgeoch@xuv.com

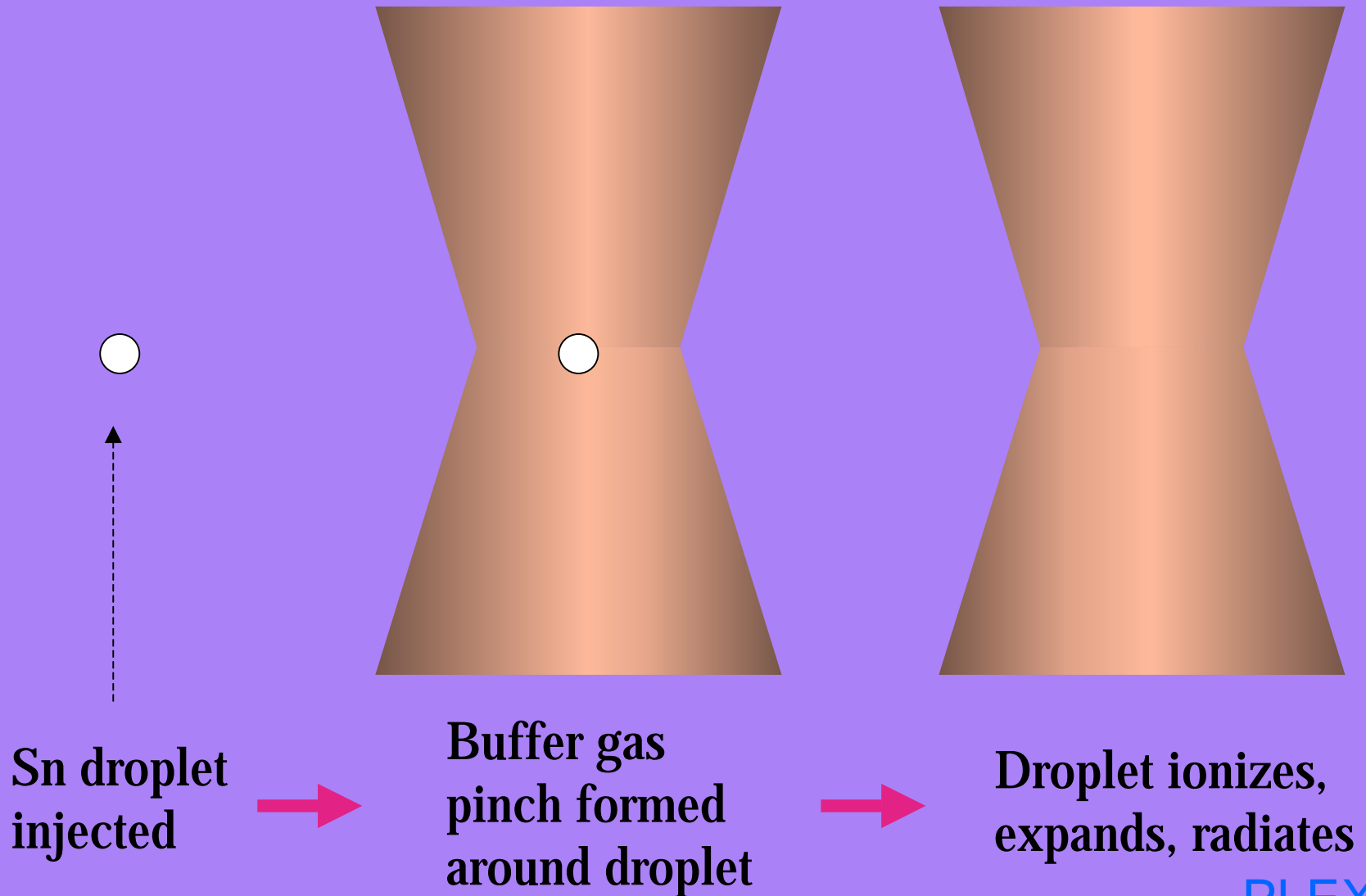
PLEX LLC, 20 Chapel St. C512, Brookline, MA 02446 USA.

## ABSTRACT

Injection of tin droplets into an argon or helium pinch discharge can provide high extreme ultraviolet (EUV) generation efficiency together with small plasma size. We calculate the rates of evaporation, ionization and expansion of a spherical solid density target in a gas pinch discharge. It is found that an initial tendency for the particle to become negatively charged reduces electron heat transport from the plasma. Negative charging is counteracted, and electron heat flux enhanced, by the generation of secondary electrons by ion impact on the surface and by photo-emission dependent on the plasma radiation spectrum. When the heat flux exceeds  $1\text{GWcm}^{-2}$  the particle can ionize and expand very rapidly to a diameter comparable to that of the pinch plasma. The time required for ionization and the final radius are each estimated as a function of particle size, plasma density and temperature. It is demonstrated that the plasma conditions in the Star Pinch EUV source are suitable for high brightness EUV generation via particle injection. Specifically, a spherical tin plasma of diameter  $600\mu\text{m}$  is predicted from an initial tin droplet of diameter  $30\mu\text{m}$ , leading to a smaller etendue than otherwise possible from a pinch plasma. Experimental progress toward an injection EUV source will be reported.

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# Principle of Injection Pinch EUV Source



# Droplet potential and heat fluxes

Maxwellian electron velocity distribution

$$f_M(\vec{v}) = n \left( \frac{m_e}{2\pi kT_e} \right)^{3/2} \exp\left( \frac{-m_e \vec{v}^2}{2kT_e} \right) \quad (1)$$

Let droplet potential be  $V_f$

For zero net current  $J_i + J_e = 0$  (2)

where  $J_i$  and  $J_e$  are the ion and electron current densities onto the droplet.

$$J_e = ne \sqrt{\frac{kT_e}{2\pi m_e}} \exp\left( -\frac{eV_f}{kT_e} \right) \quad (3).$$

$$J_i = \frac{nZ|e|}{Z} \sqrt{\frac{kT_e}{2\pi M_i}} \quad (4)$$

with ion number density  $n/Z$  and ion mass  $M_i$ . Inserting (3) and (4) into (2):-

$$\frac{eV_f}{kT_e} = \ln \sqrt{\frac{M_i}{m_e}} \quad (5).$$

The equilibrium negative droplet potential exceeds the electron temperature by 5.6 times for argon.

Electron heat flux  $W_e = \frac{n}{\sqrt{2\pi m_e}} (kT_e)^{3/2} \exp\left( -\frac{eV_f}{kT_e} \right)$  (6).

Ion heat flux  $W_i = \frac{n}{\sqrt{2\pi M_i}} (kT_e)^{3/2} \left[ \frac{1}{Z} + \frac{eV_f}{kT_e} \right]$  (7).

Negative droplet potential controls electron and ion heat fluxes. See FIG 1.

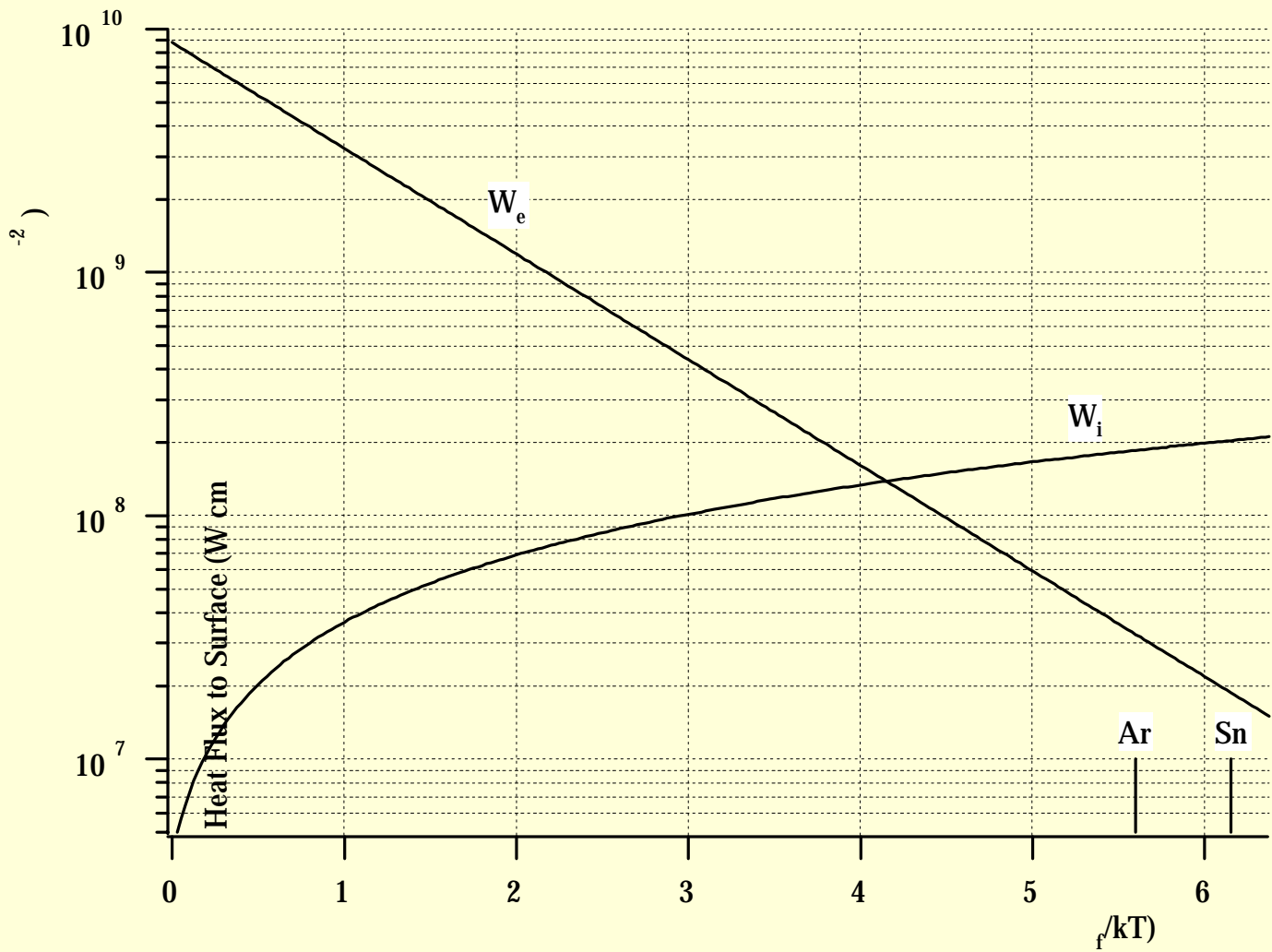


FIG 1. Electron and ion heat fluxes to the droplet surface as a function of the relative droplet potential for the case of a 30eV,  $2 \times 10^{19}$  electron cm<sup>-3</sup> argon plasma with Z=8.

# Modifiers of the Droplet Potential

Processes that act to reduce the magnitude of  $V_f$  and increase heat flux include:-

- a) **Secondary electron emission in response to ion bombardment,**
- b) **Thermionic field emission.**
- c) **Photoemission of electrons in response to plasma radiation.**

a) **Secondary Emission.** For secondary electron emission with coefficient  $\gamma_i$  e electrons per incident ion the equilibrium potential is found from

$$J_i + \gamma_i J_i / Z + J_e = 0 \quad (8)$$

giving

$$\frac{eV_f}{kT_e} = L\pi \left[ \sqrt{\frac{M_i}{m_e}} \frac{Z}{(Z + \gamma_i)} \right] \quad (9)$$

$\text{Ar}^{8+}$  incident on tin at 170eV could produce as many as 10 secondary electrons, which would modify  $eV_f/kT_e$  downward from 5.6 to approximately 4.8.

c) **Thermionic Field Emission.** In the present droplet case the sheath thickness of a few times  $\lambda_D$ , the Debye length, is only about 30nm, and with voltage  $|V_f| = 170V$  across it there can be a surface field of  $5 \times 10^7 \text{Vcm}^{-1}$ .

The ionic heat flow of  $>10^8 \text{Wcm}^{-2}$  can raise the surface to boiling point (2543K) in only 10nsec, and electron emission can then reach extremely high values via field-enhanced (Schottky) emission. The emission current is

$$J_{th} = \frac{4\pi(kT_S)^2 m_e |e|}{h^3} \exp \left[ - \left( \frac{\Phi - \sqrt{e^3 E}}{kT_S} \right) \right] \quad (10)$$

in which  $T_S$  is the surface temperature,  $\Phi$  is the work function and  $E$  is the surface electric field. This is evaluated for tin in FIG.2 Some depression of droplet potential, but self-limiting due to reduction of surface field.

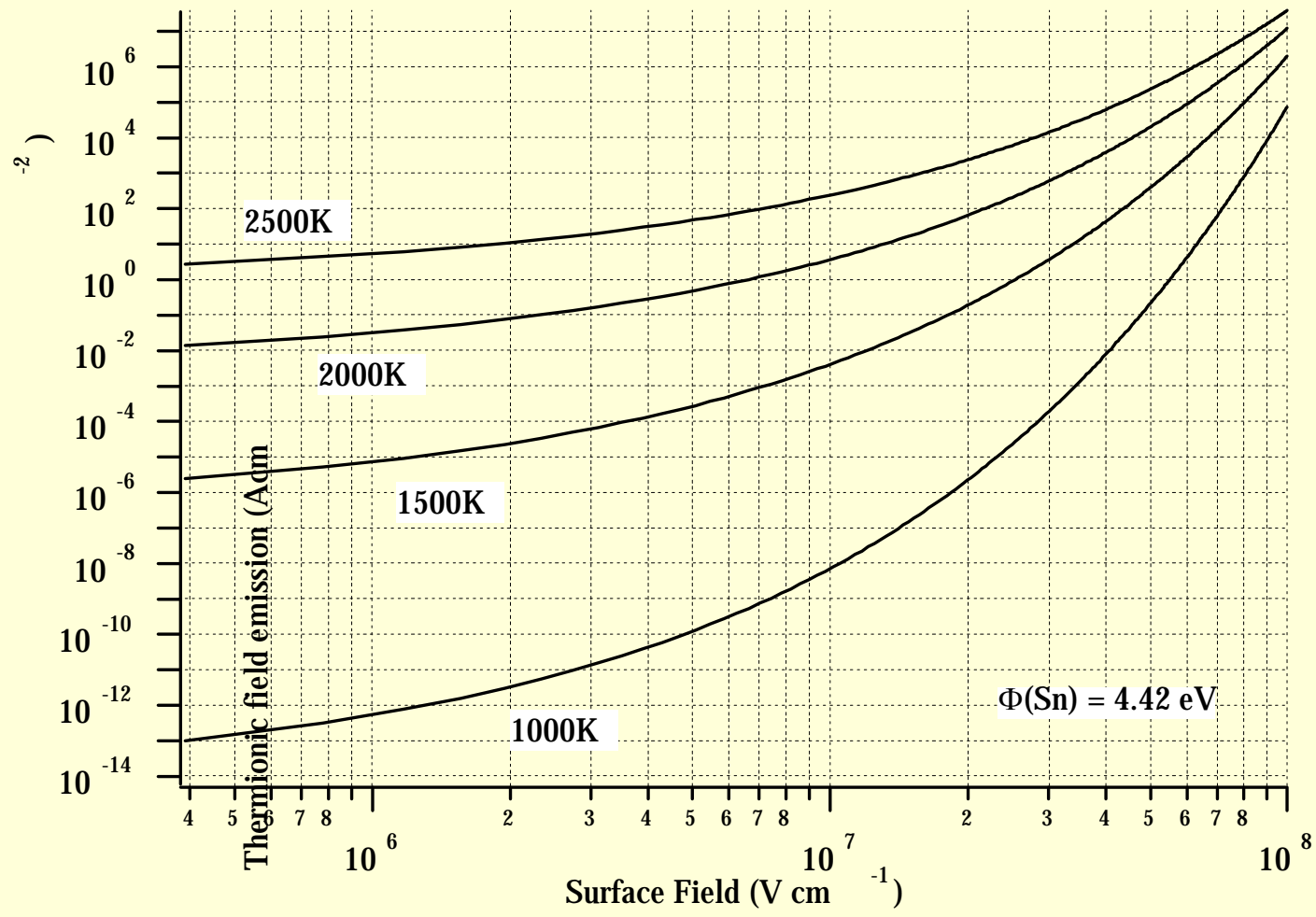


FIG. 2 Thermionic field emission current from tin surface.

**c) Photoemission.** The pinch plasma radiation field can produce surface photoelectrons and significantly reduce the droplet negative potential  $V_f$ . Consider Planck radiation flux

$$I_p(\phi) = 1.6 \times 10^4 \frac{\phi^3}{\left( e^{\phi/kT_e} - 1 \right)} \text{ W cm}^{-2} \text{ eV}^{-1} \quad (11)$$

where  $\phi$  is the photon energy and  $kT_e$  is the plasma temperature, both in electron volts.

Consider radiation from UTA at 100eV of width 10eV. The integrated radiation power can be approximated by

$$I_{UTA} = 6 \times 10^9 \eta \text{ W cm}^{-2} \quad (12)$$

where  $\eta$  = fraction of the Planck intensity reached by the peak of the UTA and we have assumed 100eV photon energy and 30eV plasma temperature.

the photoemission current becomes

$$J_{PE} = 4 \times 10^{26} \eta \gamma_{100} |e| = C_{PE} \eta \gamma_{100} |e| \text{ cm}^{-2} \text{ sec}^{-1} \quad (13)$$

where the current units will be Amperes with  $|e|$  in Coulombs and  $\gamma_{100}$  is the secondary yield of tin at 100eV. The droplet potential in the presence of radiation is given by

$$J_i + J_{PE} + J_e = 0 \quad (14)$$

leading to

$$\frac{eV_f}{kT_e} = -Ln \left\{ \sqrt{\frac{m_e}{M_i}} + \frac{C_{PE} \eta \gamma_{100}}{n} \sqrt{\frac{2\pi m_e}{kT_e}} \right\} \quad (15).$$

The potential is shown as a function of  $\eta$  in FIG. 3 and corresponding heat fluxes in FIG. 4.

In this case, depending on the value of  $\gamma_{100}$ , the potential can be depressed to zero when radiation from the UTA reaches the Planck intensity.

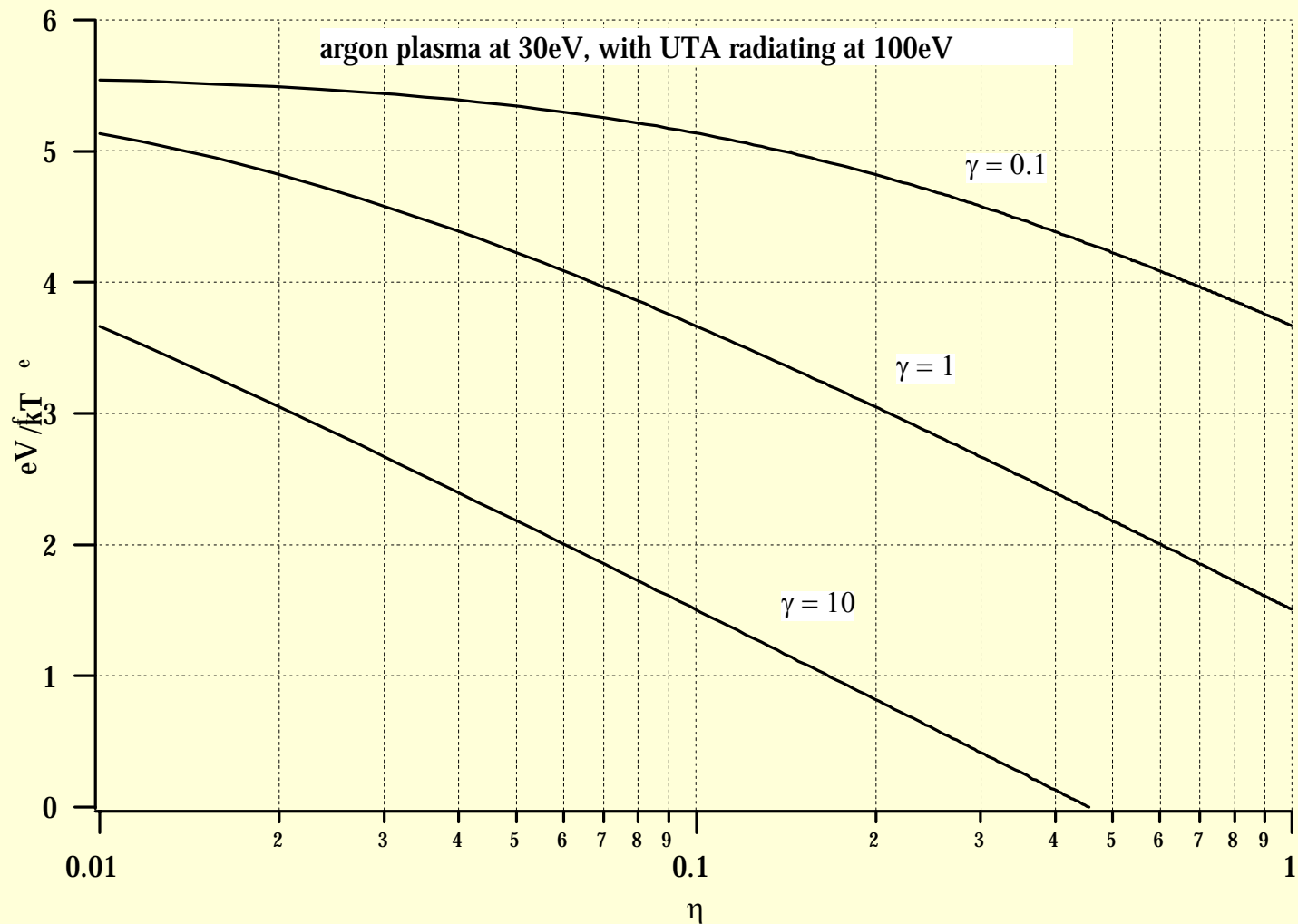


FIG 3. Depression of droplet potential by photoemission with coefficient  $\gamma$  in the presence of an unresolved transition array (UTA) at approximately 100eV with peak intensity  $\eta$  times the Planck intensity for a 30eV plasma.

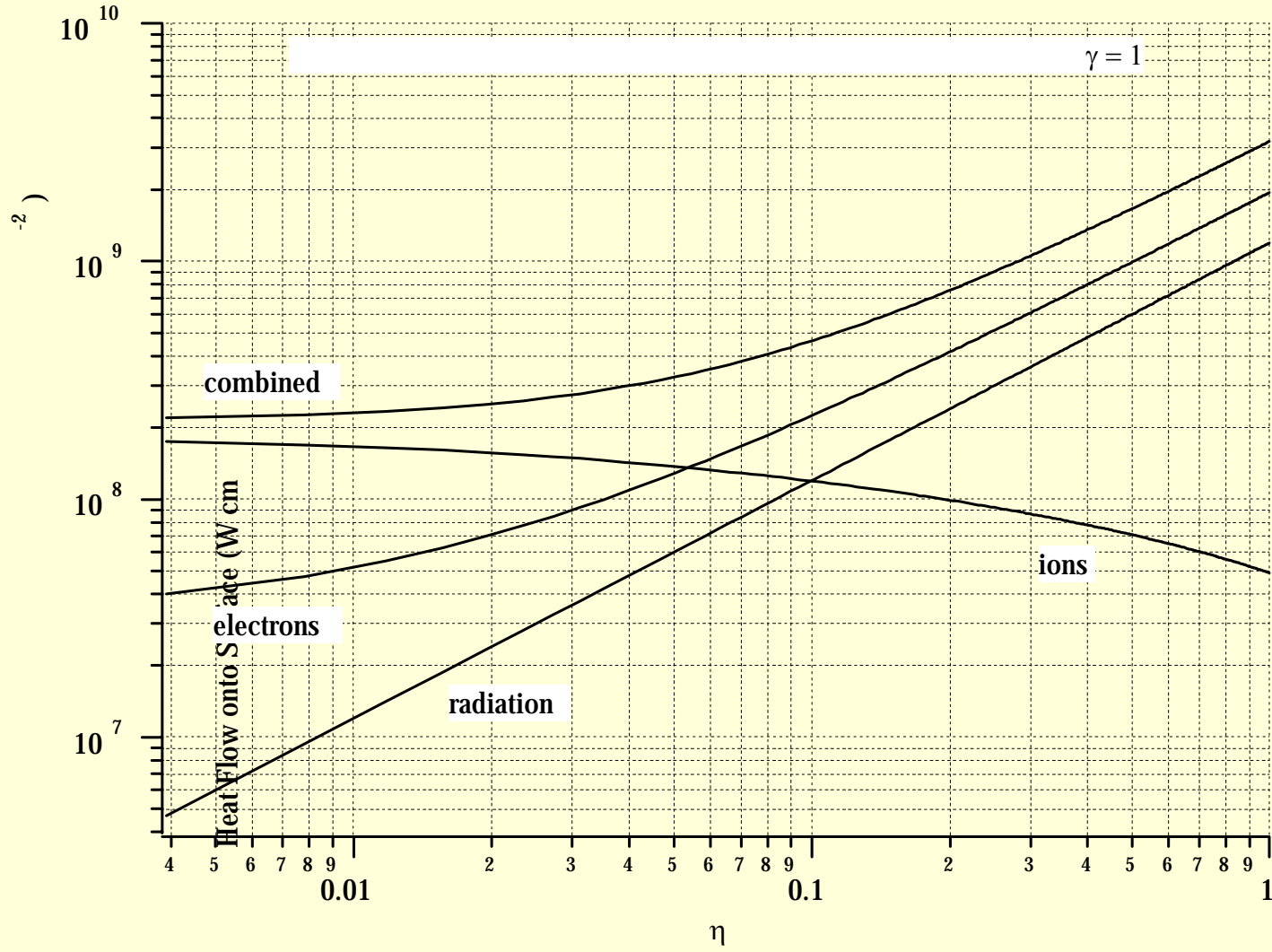


FIG 4. Effect on heat fluxes of potential depression of Fig. 3 due to the presence of an unresolved transition array (UTA) at approximately 100eV with peak intensity  $\eta$  times the Planck intensity for a 30eV plasma.

## Model of particle inflation

The droplet expands rapidly in response to the sudden application of a heat flux that can approach  $10^{10} \text{ Wcm}^{-2}$ . We estimate the rate of expansion and the likely final size of the object when the  $\text{Sn}^{7+}$  to  $\text{Sn}^{12+}$  states that emit 13.5nm radiation are accessed. As radiation builds up and lowers the droplet potential the dominant heat flow to the surface becomes that of the plasma electrons. The set of processes that takes control is akin to a laser-plasma interaction with shock propagation into the dense phase followed by greatly enhanced thermal conduction. Shock heating takes place in a time of the order of 10nsec, but the subsequent thermally driven expansion is limited by the rate of heat input.

We make the following assumptions:

a) The droplet surface, coordinate  $r_s$ , expands with radial velocity equal to the ion acoustic velocity for the tin plasma, i.e.

$$\frac{dr_s}{dt} = \sqrt{\frac{kT_e Z_{Sn}}{M_{Sn}}} \quad (16)$$

where  $T_e$  is here the electron temperature inside the tin droplet,  $Z_{Sn}$  is the average charge of tin ions and  $M_{Sn}$  is the ion mass.

b) Heat that enters via the surface is instantly communicated throughout the droplet.

c) The thermal capacity of the tin plasma increases as the average charge state increases.

d) The average charge state increases linearly with temperature (again not exact).

e) The integrated kinetic energy of expansion can be neglected relative to the internal thermal energy.

# Exponential tin droplet/plasma growth

We find exponential growth of the droplet radius according to

$$r_s = a_0 \exp(\Gamma t) \quad (17)$$

where the growth constant is given by

$$\Gamma = \left( \frac{3W_T}{\beta a_0^3 \rho_{Sn}} \right)^{\frac{1}{3}} \quad (18)$$

with

$$\beta = \frac{3(Z_{SnF} + 1)}{Z_{SnF}} + \frac{2 \sum IP}{kT_F Z_{SnF}} \quad (19)$$

and  $W_T$  = the total surface heat flux from all sources. This is true until the tin plasma temperature begins to approach the temperature of the surrounding buffer gas plasma.

The time  $t_{exp}$  taken to reach  $Z_{SnF}$ , the final average charge state, at final temperature  $T_F$  is

$$t_{exp} = \Gamma^{-1} \ln \left[ \frac{1}{a_0 \Gamma} \sqrt{\frac{Z_{SnF} k T_F}{M_{Sn}}} \right] \quad (20)$$

and then the radius of the droplet/plasma is

$$r_F = a_0 \exp(\Gamma t_{exp}) \quad (21).$$

Assuming that  $kT_F = 30 eV$  and  $Z_{SnF} = 10$  we evaluate typical expansion times and radii in FIG. 5 and FIG. 6

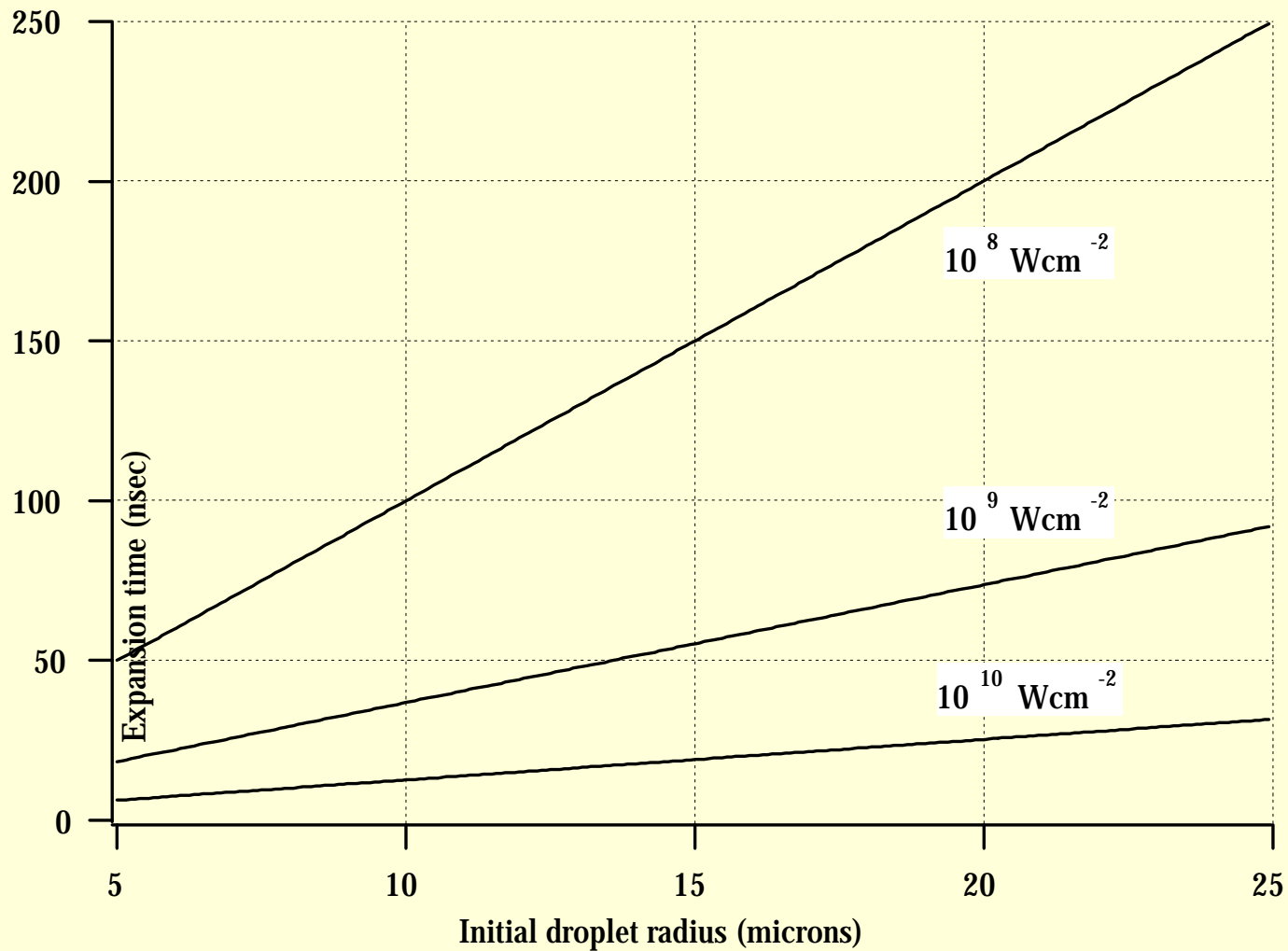


FIG 5. Expansion time to tin plasma temperature of 30eV as a function of initial radius and plasma power flux onto the surface of a tin droplet.

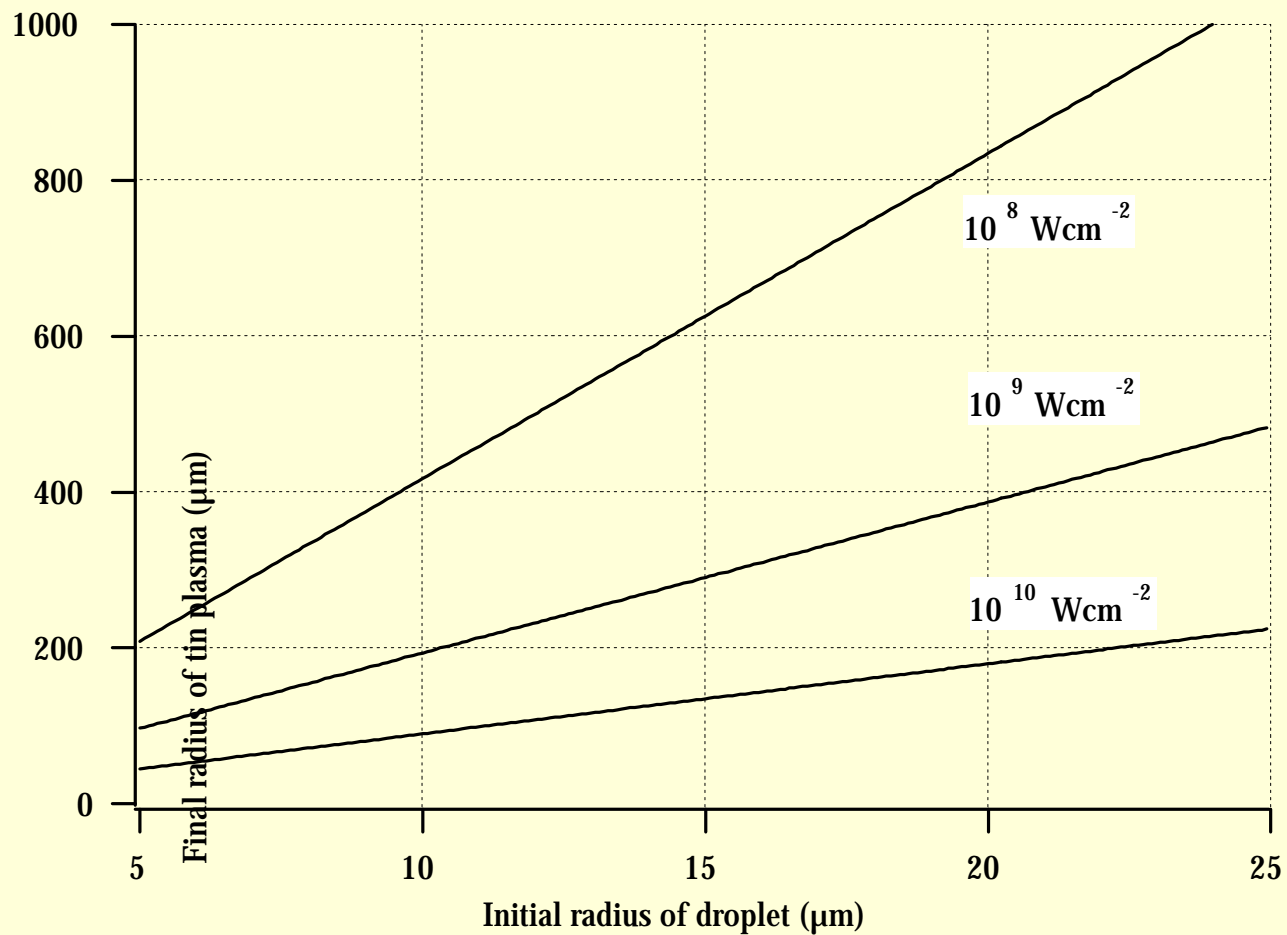
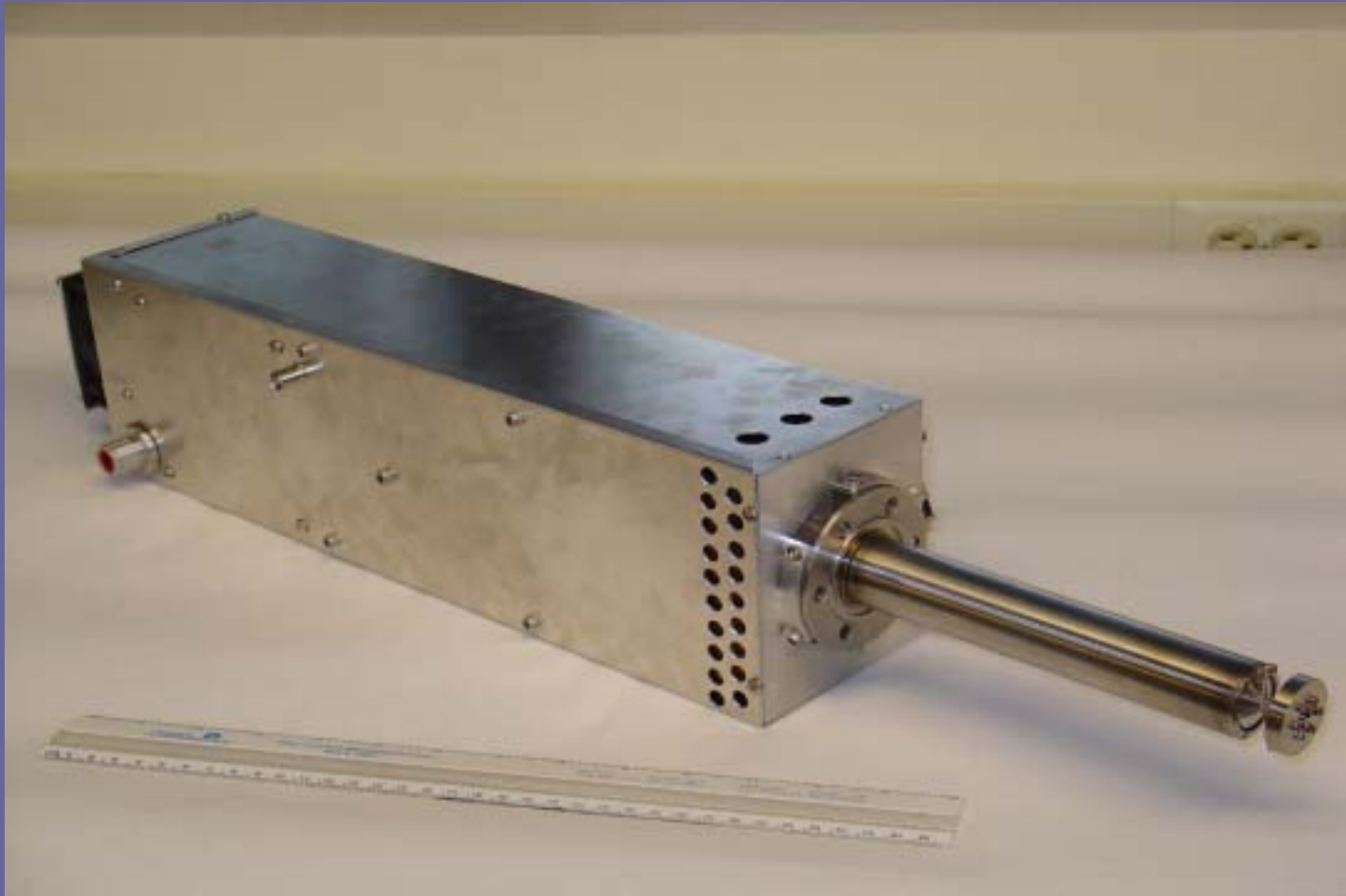


FIG. 6. Radius of tin plasma at temperature of 30eV as a function of initial radius and plasma power flux onto the surface of a tin droplet.

# Tin Droplet Specifications

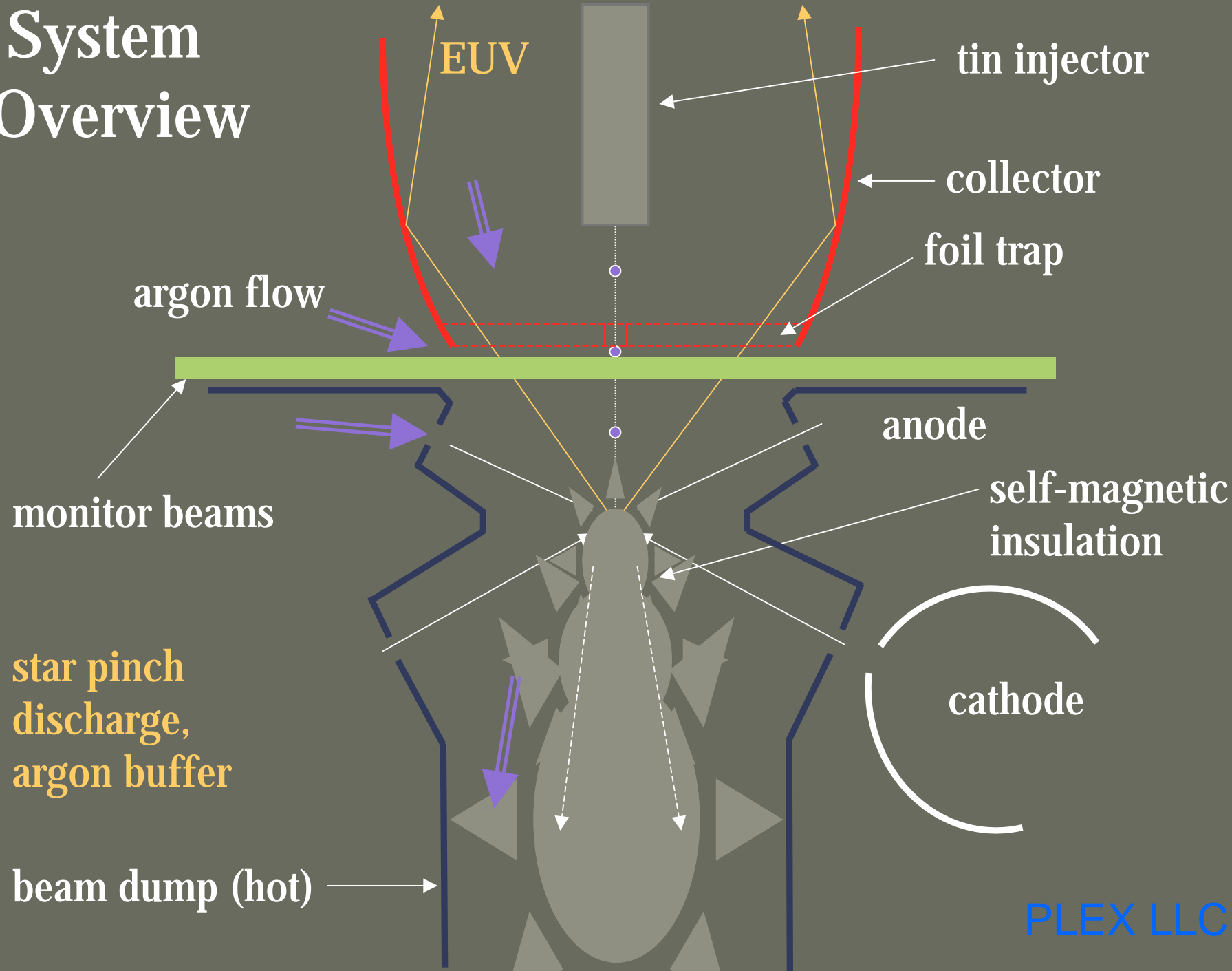
	Size ( $\mu\text{m}$ )	$\Delta r$ ( $\mu\text{m}$ )	$\Delta z$ ( $\mu\text{m}$ )	Velocity ( $\text{m sec}^{-1}$ )	Rep.rate (kHz)
DPP (injection pinch)	30	50	50	>20	6
LPP	20	2	2	>30	10
PLEX to date	20-50	2	10	12-46	>0.1

Approach: impulse ejection of liquid tin thru' nozzle



**PLEX tin droplet generator**

# System Overview



# Injection Pinch Discharge EUV Source

## **Conclusions and Status:**

Star Pinch plasma 30eV,  $2 \times 10^{19}$ , 100ns  
should ionize mass-limited 30 $\mu$ m tin droplet\*

13.5nm emission expected from 600 $\mu$ m diameter tin plasma

PLEX has generated tin droplets suitable for injection pinch

Alignment of droplet stream with plasma is a current challenge

*\*Forthcoming paper in J. Phys. D special issue on EUV sources*